Intel® Server Board S1600JP Product Family

Rack optimized, performance single socket server board for HPC and embedded appliances

Supports the Intel® Xeon® processor E5-2600v2 product family

A performance single-socket system featuring a half-width board, rich in I/O (40 Gen3 lanes) for a streamlined 1U rack mount server presentation. Designed for cost-effective execution, the Intel® Server Board S1600JP features support for one Intel® Xeon® processor E5-2600 or E5-1600 product family, 8 DIMMs, and front I/O support for convenient 1U rack deployment. Models available with optional support for Intel® Xeon Phi™ coprocessor. Perfect for applications requiring a powerful, reliable server solution with extended warranty options.

Supports

- Single socket for Intel® Xeon® processor E5-2600v2 or E5-1600v2
- One Intel® Xeon Phi™ coprocessor
- 8 LR/U/R-DIMMs at up to 1866MT/s
- Single or dual highly efficient power supply options, including DC power
- Maximum 2.5" or 3.5" HDD storage configuration in 1U rack

80 PLUS PLATINUM

intel inside™ SERVER BOARD

intel inside™ XEON®

intel inside™ XEON PHI™

Flexible Processor Support

Supports one Intel® Xeon® processor E5-2600 or E5-1600

Expandable Processing Power

Optional Intel® Xeon Phi™ coprocessor for HPC application performance

Strong I/O Support

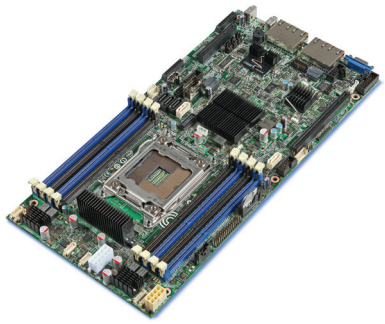
Provides 7 USB headers including a front connection

For more information on Intel server solutions visit: intelserveredge.com

For more information on Intel server products visit: intel.com/go/serverproducts

For product specifications visit: ark.intel.com

For regulatory information visit: intel.com/support/motherboards/server/sb/CS-32524.htm



Intel® Server Board S1600JP Product Family Technical Specifications

Form Factor	1U rack: 1.75" x 17.2" x 24.75"
Server Board Included	S1600JP4: Two integrated dual port 1 GbE Ethernet Controllers
Processors Supported	One Intel® Xeon® processor E5 2600/1600 or E5 2600v2/1600v2 product family, up to 135W One Intel® Xeon Phi™ coprocessor[1]
Total Slots	3
Slot Types	2 PCI Express* 3.0 x16 1 PCI Express 3.0 x8
Memory Capacity	8 LR / U / RDIMMs with up to 1866MT/s, ECC 256 GB max
Drive Options	8 x 2.5" or 4 x 3.5" hot-swap HDDs
System Cooling	Redundant cooling fans
Power Supply Options	450W AC Redundant PSU (Gold Efficiency), 750W AC PSU (Platinum Efficiency) or 450W DC Redundant PSU
Module Upgrades	Intel® I/O Module Intel® Integrated RAID ROC or IOC Module Intel® Remote Management Module 4

Product does not include memory, processors, or hard drives. For compatibility information please refer to the configuration guide at www.intel.com/support

1U 2.5" Drives

R1208JP4GS
8 x 2.5" hot-swap HDD
1 x 750W AC PSU

R1208JP4OC
8 x 2.5" hot-swap HDD
2 x 450W AC PSU

R1208JP4TC
8 x 2.5" hot-swap HDD
2 x 450W DC PSU

1U 3.5" Drives

R1304JP4GS
4 x 3.5" hot-swap HDD
1 x 750W AC PSU

R1304JP4OC
4 x 3.5" hot-swap HDD
2 x 450W AC PSU

R1304JP4TC
4 x 3.5" hot-swap HDD
2 x 450W DC PSU

[1] Intel® Xeon Phi™ coprocessor support depends on the board and chassis configuration. See your sales representative for more details

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